

Surface-mounting Tactile Switch for High-density Packaging

- Dust-sealed construction provides high reliability in locations exposed to dust.
- SMD Tactile Switch ideal for high-density mounting.
- Sealed construction conforming to IP64 (IEC-529). Can be washed after soldering.
- Ground terminal available to protect against static electricity.



Ordering Information

6 x 6-mm-type B3S-1000

			Without ground terminal		With ground terminal	
			Bags (100 Switches)	Embossed tape (1,000 Switches)	Bags (100 Switches)	Embossed tape (1,000 Switches)
Standard-force	1.57 N {160 gf}	4.3 mm	B3S-1000	B3S-1000P	B3S-1100	B3S-1100P
High-force	2.25 N {230 gf}		B3S-1002	B3S-1002P	B3S-1102	B3S-1102P

Note: Switches in bags must be ordered in units of 100 Switches, and Switches on embossed tape must be ordered in units of 3,000 Switches.

Specifications

■ Ratings/Characteristics

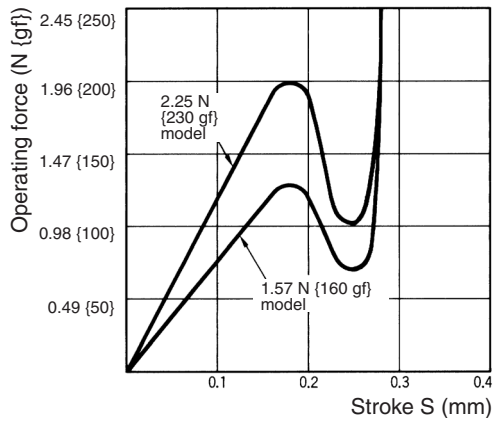
Switching capacity	5 to 24 VDC, 1 to 50 mA (resistive load)
Insulation voltage	30 VDC
Ambient temperature	Operating: -25°C to 70°C (with no icing)
Ambient humidity	Operating: 35% to 85%
Contact configuration	SPST-NO
Contact resistance	100 mΩ max. (initial value) (rated: 1 mA, 5 VDC)
Insulation resistance	100 MΩ min. (at 250 VDC)
Dielectric strength	500 VAC, 50/60 Hz for 1 min
Bounce time	5 ms max.
Vibration resistance	Malfunction: 10 to 55 Hz, 1.5-mm double amplitude
Shock resistance	Destruction: 1,000 m/s ² {approx. 100G} max. Malfunction: 100 m/s ² {approx. 10G} max.
Life expectancy	Standard force models (1.57 N): 500,000 operations min. High-force models (2.25 N): 300,000 operations min.
Weight	Approx. 0.3 g

■ Operating Characteristics

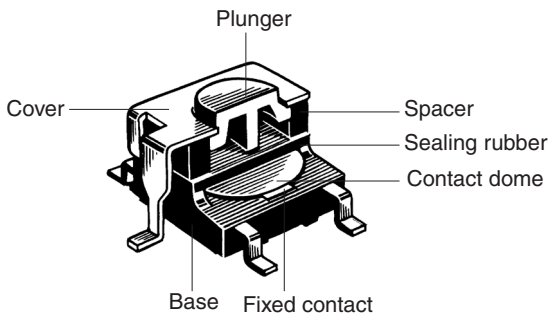
Item	B3S-1□00	B3S-1□02
Operating force (OF)	1.57 N {160 gf} max.	2.25 N {230 gf} max.
Releasing force (RF)	0.2 N {20 gf} min.	0.49 N {50 gf} min.
Pretravel (PT)	0.25 ^{+0.2} / _{-0.1} mm	

Engineering Data

**Operating Force vs. Stroke
(Typical)**



Nomenclature

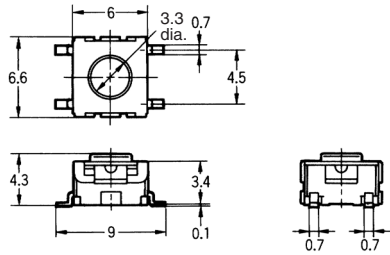
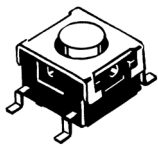


Dimensions

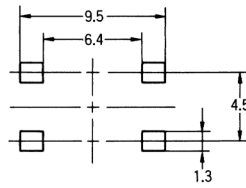
Note: All units are in millimeters unless otherwise indicated. Unless otherwise specified, a tolerance of ± 0.4 mm applies to all dimensions.

Without Ground Terminal

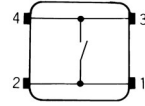
B3S-1000
B3S-1002



PCB Mounting (Top View)

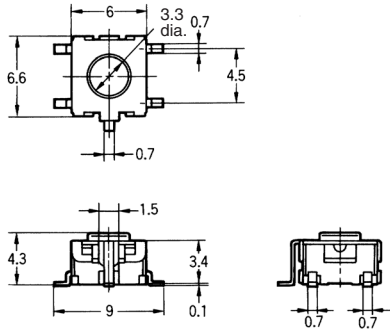
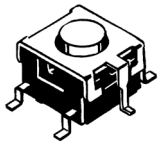


Terminal Arrangement /Internal Connections (Top View)

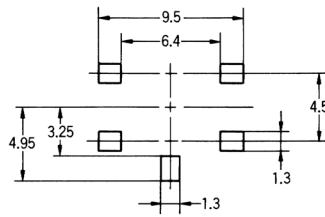


With Ground Terminal

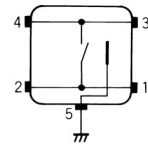
B3S-1100
B3S-1102



PCB Mounting (Top View)



Terminal Arrangement /Internal Connections (Top View)



Precautions

Be sure to read the precautions common to all Tactile Switches on pages 5 to 7 for correct use.

ALL DIMENSIONS SHOWN ARE IN MILLIMETERS.
To convert millimeters into inches, multiply by 0.03937. To convert grams into ounces, multiply by 0.03527.

Safety Precautions

■ Precautions for Safe Use

Use the Switch within the rated voltage and current ranges, otherwise the Switch may have a shortened life expectancy, radiate heat, or burn out. This particularly applies to the instantaneous voltages and currents when switching.

■ Precautions for Correct Use

Storage

To prevent degradation, such as discoloration, in the terminals during storage, do not store the Switch in locations that are subject to the following conditions.

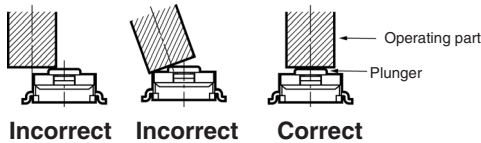
1. High temperature or humidity
2. Corrosive gases
3. Direct sunlight

Handling

1. Operation

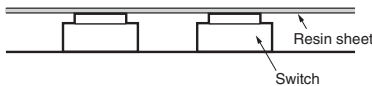
Do not repeatedly operate the Switch with excessive force. Applying excessive pressure or applying additional force after the plunger has stopped may deform the disc spring of the Switch, resulting in malfunction. In particular, applying excessive force to Side-operated Switches may damage the caulking, which in turn may damage the Switch. Do not apply force exceeding the maximum (29.4 N for 1 minute, one time) when installing or operating Side-operated Switches.

Be sure to set up the Switch so that the plunger will operate in a straight vertical line. A decrease in the life of the Switch may result if the plunger is pressed off-center or from an angle.



2. Dust Protection

Do not use Switches that are not sealed in dust-prone environments. Doing so may cause dust to penetrate inside the Switch and cause faulty contact. If a Switch that is not sealed must be used in this kind of environment, use a sheet or other measure to protect it against dust.



PCBs

The Switch is designed for a 1.6-mm thick, single-side PCB.

Using PCBs with a different thickness or using double-sided, through-hole PCBs may result in loose mounting, improper insertion, or poor heat resistance in soldering. These effects will occur, depending on the type of holes and patterns of the PCB. Therefore, it is recommended that a verification test is conducted before use.

If the PCBs are separated after mounting the Switch, particles from the PCBs may enter the Switch. If PCB particles or foreign particles from the surrounding environment, workbench, containers, or stacked PCBs become attached to the Switch, faulty contact may result.

Soldering

1. General Precautions

Before soldering the Switch on a multilayer PCB, test to confirm that soldering can be performed properly. Otherwise the Switch may be deformed by the soldering heat on the pattern or lands of the multilayer PCB.

Do not solder the Switch more than twice, including rectification soldering. An interval of five minutes is required between the first and second soldering.

2. Automatic Soldering Baths (B3F, B3W, B3WN, B3M, B3J)

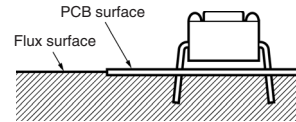
Soldering temperature: 260°C max.

Soldering time: 5 s max. for a 1.6-mm thick single-side PCB

Preheating temperature: 100°C max. (ambient temperature)

Preheating time: Within 60 s

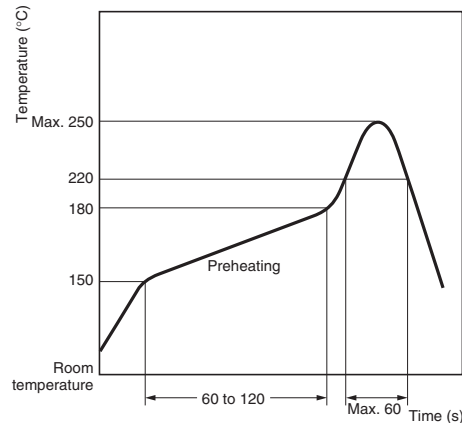
Make sure that no flux will rise above the level of the PCB. If flux overflows onto the mounting surface of the PCB, it may enter the Switch and cause a malfunction.



3. Reflow Soldering (Surface Mounting)

Solder the terminals within the heating curve shown in the following diagram.

B3S, B3SN, B3FS



Note: The above heating curve applies if the PCB thickness is 1.6 mm.

The peak temperature may vary depending on the reflow bath used. Confirm the conditions beforehand.

Do not use an automatic soldering bath for surface-mounted Switches. The soldering gas or flux may enter the Switch and damage the Switch's push-button operation.

4. Manual Soldering (All Models)

Soldering temperature: 350°C max. at the tip of the soldering iron
Soldering time: 3 s max. for a 1.6-mm thick, single-side PCB

Before soldering the Switch on a PCB, make sure that there is no unnecessary space between the Switch and the PCB.

Washing

1. Washable and Non-washable Models

Washable (sealed types)	B3W, B3WN, B3S, B3SN
Non-washable (standard types)	B3F, B3FS, B3M, B3J, B3DA, B3D

Standard Switches are not sealed, and cannot be washed. Doing so will cause the washing agent, together with flux or dust particles on the PCB, to enter the Switch, resulting in malfunction.

2. Washing Methods

Washing equipment incorporating more than one washing bath can be used to clean washable models, provided that the washable models are cleaned for one minute maximum per bath and the total cleaning time does not exceed three minutes.

3. Washing Agents

Apply alcohol-based solvents to clean washable models. Do not apply any other agents or water to clean any washable model, as such agents may degrade the materials or performance of the Switch.

4. Washing Precautions

Do not impose any external force on washable models while washing.

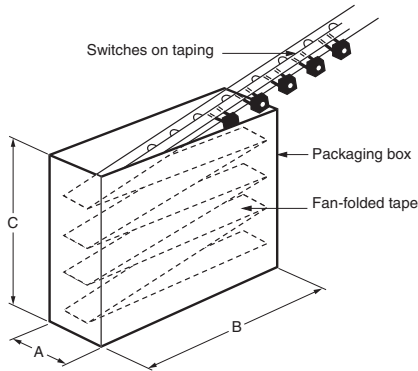
Do not clean washable models immediately after soldering. The cleaning agent may be absorbed into the Switch through respiration as the Switch cools. Wait for at least three minutes after soldering before cleaning washable models.

Do not use Sealed Switches while submersed in water or in locations exposed to water.

Switch Packaging (Taping Specification Models)

1. Radial Types

The tape is packaged by fan-folding into the box, as shown in the following diagram.



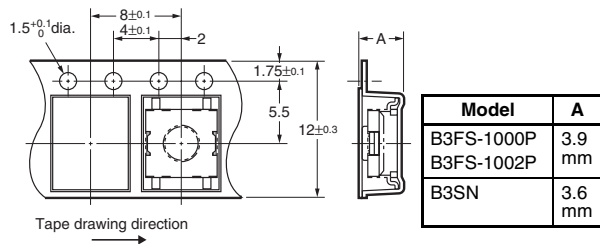
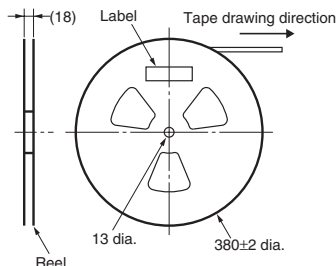
Model	A	B	C
B3F	50 mm	325 mm	275 mm
B3WN	53 mm	326 mm	350 mm

Do not apply any external force to the packaging box, or subject it to vibration. Doing so may deform the Switch terminals.

Remove the tape slowly, making sure that the Switches are not entangled or caught. Otherwise the terminals may be deformed.

Do not store the packaged Switches in locations subject to high temperatures or high humidity. The packaging boxes are sealed with paper tape and are not airtight. Storing the packaged Switches in locations with high temperature or high humidity may result in deterioration of the tape and Switches, and long-term storage under such conditions may cause discoloration of the Switch terminals.

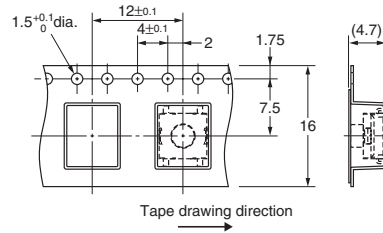
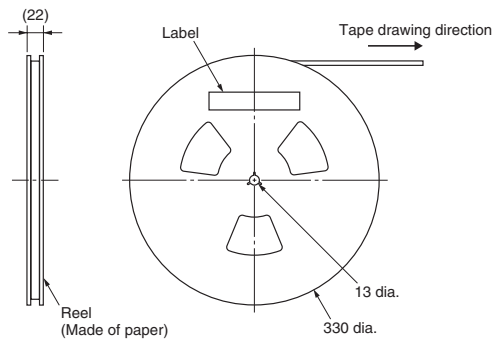
2. Packaging Specifications for Embossed Taping (B3FS-1000P/-1002P, B3SN)



Standards	Conforms to JEITA.
Package	3,000 Switches
Heat resistance	50°C for 24 hours (without deformation)

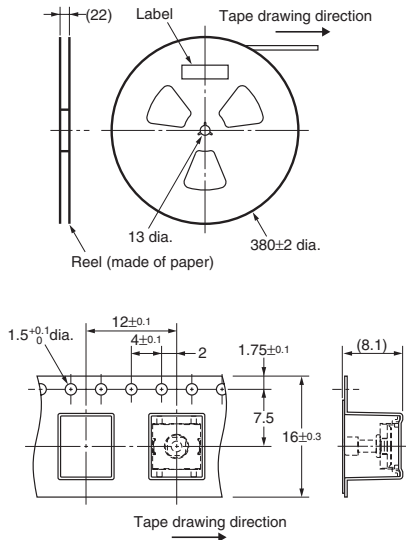
Note: Switches with ground terminals are packaged with the ground terminal on the opposite side of the guide hole.

B3FS-1010P



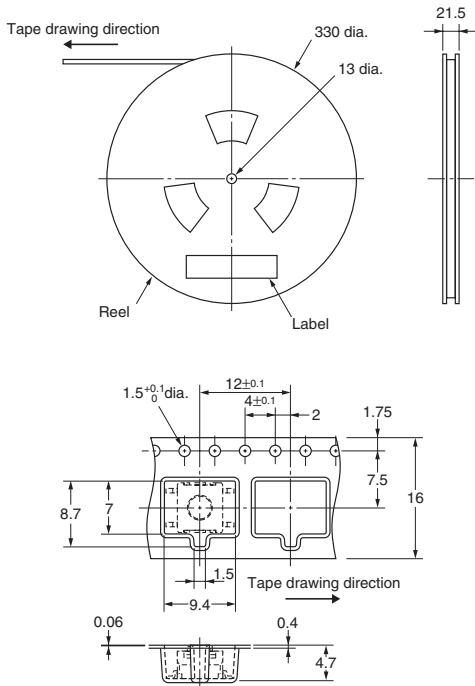
Standards	Conforms to JEITA.
Package	1,000 Switches
Heat resistance	60°C for 24 hours (without deformation)

B3FS-1050P



Standards	Conforms to JEITA.
Package	1,000 Switches
Heat resistance	60°C for 24 hours (without deformation)

B3S



Standards	Conforms to JEITA.
Package	1,000 Switches
Heat resistance	50°C for 24 hours (without deformation)

Note: Switches with ground terminals are packaged with the ground terminal on the opposite side of the guide hole.

LEDs (B3J)

Make sure that the polarity of the LEDs is correct. The polarity is not indicated on the Switch, but the positive pole is located on the back surface of the Switch on the side without the OMRON mark.

Connect limiting resistors to the LEDs. The Switch does not have built-in limiting resistors, so satisfy the LED characteristics by obtaining the limiting resistance according to the following formula based on the voltage to be used.

$$\text{Limiting resistance (R)} = \frac{(\text{Voltage used (E)} - \text{LED forward voltage (VF)})}{\text{LED forward current (IF)}} \quad (\Omega)$$

